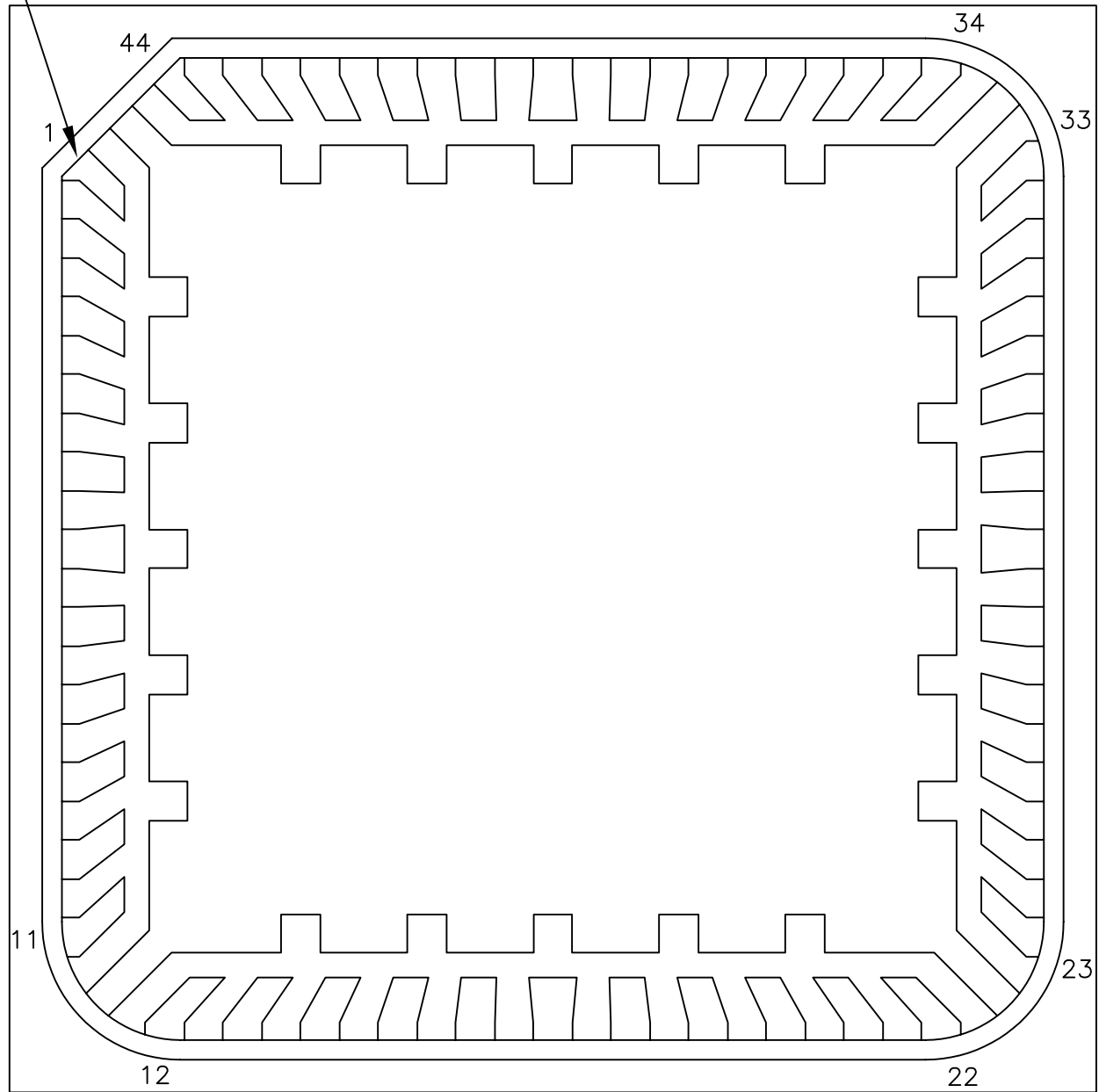


BONDING PAD #1



DEVICE TYPE:				<p align="center">SEMPAC, INC. Open-Pak™ Technologies www.sempac.com 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006</p>			
CUSTOMER:		DIE SIZE:					
WIRE TYPE/ SIZE:		NO. OF WIRES:					
<p>THIRD ANGLE PROJECTION</p>	REVISIONS						
	ECN NO.	DATE	DESCRIPTION	APPROVED			
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER DO NOT SCALE DRAWING	10500	10/27/05	PRODUCTION RELEASE	D.BENANDO	44 Lead 7mm x 7mm MLP Open-Pak Bonding Diagram		
DRAWN BY W. GRIFFITTS	DATE 10/26/05	PACKAGE SIZE: 7.00mm x 7.00mm	SIZE A	PART NO. MLP7X7-44-OP-01	REV 3		
APP BY P. FLASKERUD	DATE 10/26/05	DIE PAD SIZE: 5.20mm x 5.20mm	SCALE 24X	CAD FILE MLP7X7-44-OP-01-B-R3.DWG	SHEET 1 OF 1		